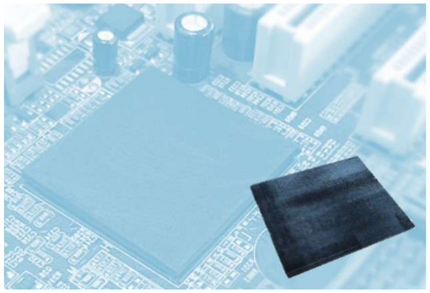
Carbon Fiber Thermal Pad



Features:

1. Ultra-high thermal conductivity in the vertical direction, low thermal impedance.
2. Good flexibility, resilience, and thermal stability.
3. Natural tacky, easy to use and rework.

Applications:

5G base station RRU, chips, capacitors, memory/VRAM particles, hard drives, control boards, splitters, relays.

Model	Thermal Conductivity W/m·K	Thermal Impedance, ℃*in^2/W at 20psi, 1mm	Thickness, mm	Standard Hardness, Shore 00	Custom Hardness, Shore 00	Dielectric Strength, kV/mm	Operating Temp., ℃
JSCSF-0015	15.0	0.28	0.3~12.0	40/60	40~90	0.1	-50~160
JSCSF-0020	20.0	0.18	0.3~12.0	40/60	40~90	0.1	-50~160
JSCSF-0025	25.0	0.12	0.3~12.0	40/60	40~90	0.1	-50~160
JSCSF-0030	30.0	0.10	0.3~12.0	40/60	40~90	0.1	-50~160
JSCSF-0040	40.0	0.08	0.3~12.0	40/60	40~90	0.1	-50~160
JSCSF-0045	45.0	0.07	0.3~12.0	40/60	40~90	0.1	-50~160